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TFT | CHARACTER | UWVD | FSC | SEGMENT | CUSTOM | REPLACEMENT

TFT Display Module

Part Number E28RA-I-CW384-R

Overview:

- 2.8-inch TFT (50.5x69.7)
- 240 320
- 8/9/16/18-bit MCU Interface
- 3/4-wire SPI Interface
- All View

- Transmissive, IPS
- Wide Temperature
- Resistive Touch Panel
- 384 nits
- TFT IC: ST7789V
- RoHS Compliant



Description

This is a color active matrix TFT (Thin Film Transistor) LCD (Liquid Crystal Display) that uses amorphous silicon TFT as a switching device. This model is composed of a transmissive type TFT LCD Panel, driver circuit, 4-wire resistive touch panel, and a backlight unit. The resolution of the 2.8" TFT LCD contains 240(RGB)x320 pixels and can display up to 262k colors.

TFT Features

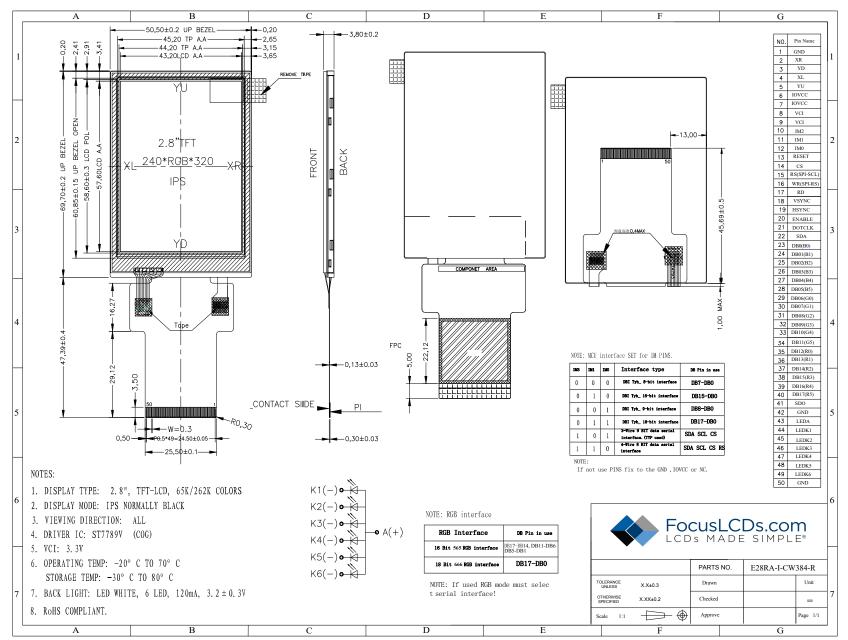
Low Input Voltage: 3.3V Display Colors: 65k/262k Interface: 8/9/16/18-bit MCU 3/4SPI+16/18-bit RGB 3/4-wire Serial

General Information Items	Specification Main Panel	– Unit	Note
TFT Display area (AA)	43.20(H) x 57.60(V) (2.8 inch)	mm	-
Driver Element	TFT active matrix	-	-
Display Colors	65k/262k	colors	-
Number of pixels	240(RGB)x320	dots	-
TFT Pixel arrangement	RGB vertical stripe	-	-
Pixel Pitch	0.153 (H)x0.153(V)	mm	-
Viewing angle	ALL	o'clock	-
TFT Controller IC	ST7789V	-	-
TFT Interface	MCU, SPI+RGB, SPI	-	-
Display mode	Transmissive/ Normally Black	-	-
Operating temperature	-20~+70	°C	-
Storage temperature	-30~+80	°C	-

Mechanical Information

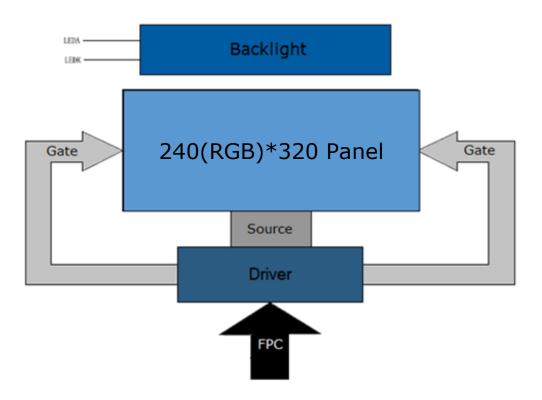
Item		Min	Тур.	Max	Unit	Note
	Horizontal (H)		50.50		mm	-
Module	Vertical (V)		69.70		mm	-
Size	Depth (D)		3.80		mm	-
	Weight		TBD		g	

1. Outline Dimensions





2. Block Diagram





3. Input Terminal Pin Assignment Recommended TFT Connector: FH12S-50S-0.5SH(55) 3.

Recommended RTP Connector: FH33-4S-1SH(10)

NO.	Symbol	Description					I/O		
1	GND	Ground	Ground						
2	XR	Touch panel right glass to	Touch panel right glass terminal						
3	YD	Touch panel bottom film	terminal				A/D		
4	XL	Touch panel left glass ter	Touch panel left glass terminal						
5	YU	Touch panel top film terr	ninal				A/D		
6	IOVCC	Supply voltage (1.65-3.3)	V)				Р		
7	IOVCC	Supply voltage (1.65-3.3)	V)				Р		
8	VCI	Supply voltage (3.3V)					Р		
9	VCI	Supply voltage (3.3V)					Р		
		Interface selection	IM3	IM2	IM0	Pins used			
		DBI 8-bit	0	0	0	DB7-DB0			
	IM3	DBI 16-bit	0	1	0	DB15-DB0			
10-12	IM2	DBI 9-bit	0	0	1	DB8-DB0	Ι		
	IM0	DBI 18-bit	0	1	1	DB17-DB0			
		3-wire, 9-bit SPI	1	0	1	SDA SCL CS			
		4-wire, 8-bit SPI	1	1	0	SDA SCL CS RS			
13	RESET	Reset signal of the device active low.	e. Must be a	pplied to pro	perly initializ	the device. Signal is	Ι		
14	CS	Chip select pin. When no	t used this	nin can he fix	red low		Ι		
15	RS(SPI_SCL)	Data or command signal for the parallel MCU interface. RS=1: data is selected, RS=0: command is selected. The clock for the serial interface. If not used, pin to VCI or GND.					I		
16	WR(SPI_RS)	Write signal in the parall the 4-wire serial interface			-	neter select signal for	Ι		
17	RD	Read signal for the MCU				VCI or GND.	0		
18	VSYNC	Frame synchronizing sign					Ι		
19	HSYNC	Line synchronizing signa					Ι		
20	ENABLE	Data enable signal for the			1		I		
20	DOTCLK	Dot clock signal for the H					I		
22	SDA	Serial input signal. The dused, pin to VCI or GND	ata is applie		-		I		
23-40	DB0-DB17	18-bit parallel bi-directio when not used.	nal data bu	t for the RGE	and MCU ir	nterfaces. Fix to GND	I/O		
41	SDO	Serial data output for the	SPI interfa	ce.			Ι		
42	GND	Ground					Р		
43	LEDA	Anode pin of the backlig	ht				Р		
44	LEDK1	Cathode pin of the backli					P		
45	LEDK2	Cathode pin of the backli	-				Р		
46	LEDK3	Cathode pin of the backli	-				Р		
47	LEDK4	Cathode pin of the backli	0				Р		
48	LEDK5	Cathode pin of the backli	-				Р		
49	LEDK6	Cathode pin of the backli	-				P		
50	GND	Cathode pin of the backli	-				Р		

I: Input, O: Output, P: Power



4. LCD Optical Characteristics

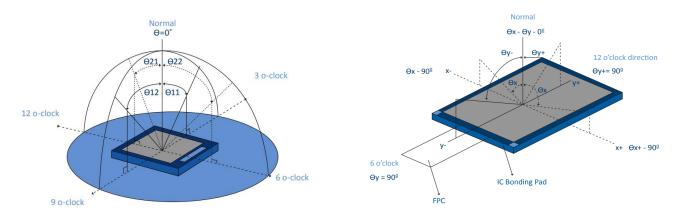
4.1 **Optical Specifications**

Item		Symbol	Condition	Min	Тур.	Max	Unit	Note
Color Gar	nut	S%			60		%	(3)
Contrast R	atio	CR		600	800		%	(2)
Response Time	Rising Falling	TR+TF			30	40	ms	(4)
	W/L 14	Wx	$\theta = 0$	0.288	0.308	0.328		
	White	W _Y	Normal viewing	0.310	0.330	0.350		
	Dal	R _X	-	0.621	0.641	0.661		
Color Filter	Red	R _Y	angle	0.317	0.337	0.357		(5)(6)
Chromaticity	Green	G _X		0.254	0.274	0.294		(5)(6)
	Green	Gy		0.540	0.560	0.580		
	Dlue	B _X		0.121	0.141	0.161		
	Blue	B _Y		0.093	0.113	0.133		
		ΘL			80			
	Hor.	ΘR	CR≥10		80		1	(1)(6)
Viewing Angle	g Angle				80		degrees	(1)(6)
	Ver.	ΘΒ			80		<u> </u>	
Option View D	Option View Direction ALL							(1)



Optical Specification Reference Notes:

(1) Definition of Viewing Angle: The viewing angle is the angle at which the contrast ratio is greater than 10. The viewing angles are determined for the horizontal or 3,9 o'clock direction and the vertical or 6,12 o'clock direction with respect to the optical axis which is normal to the LCD surface.



(2) Definition of Contrast Ratio (Cr): measured at the center point of panel. The contrast ratio (Cr) measured on a module, is the ratio between the luminance (Lw) in a full white area (R=G=B=1) and the luminance (Ld) in a dark area (R=G=B=0).

$$Cr = \frac{Lw}{Ld}$$

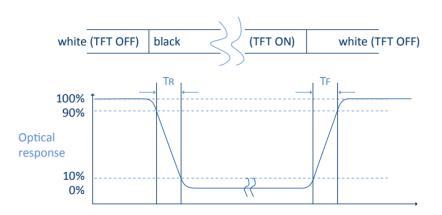
(3) Definition of transmittance (T%): The transmittance of the panel including the polarizers is measured with electrical driving. The equation for transmittance Tr is:



Io = the brightness of the light source.

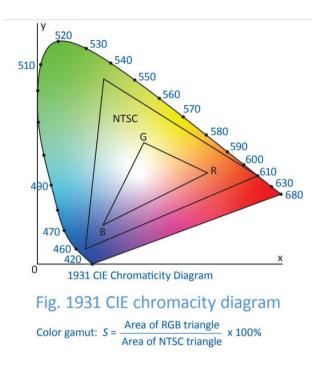
It = the brightness after panel transmission

(4) Definition of Response Time (Tr, Tf): The rise time 'Tr' is defined as the time for luminance to change from 90% to 10% as a result of a change of the electrical condition. The fall time 'Tf' is defined as the time for luminance to change from 10% to 90% as a result of a change of the electrical condition.



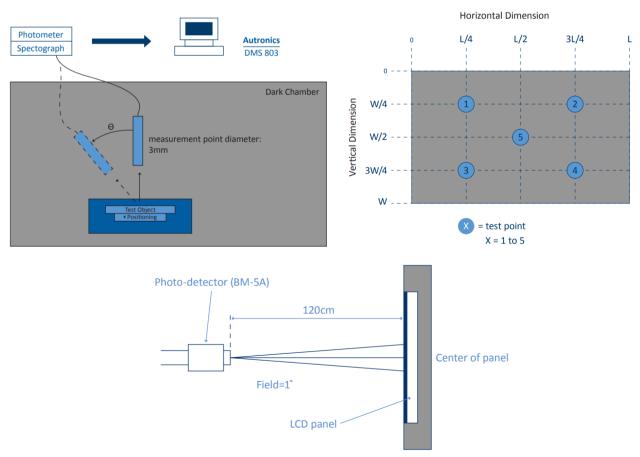


(5) Definition of Color Gamut: Measuring machine CFT-01. NTSC's Primaries: R(x,y,Y),G(x,y,Y), B(x,y,Y). FPM520 of Westar Display Technologies, INC., which utilized SR-3 for Chromaticity and BM-5A for other optical characteristics. The color chromaticity shall be calculated from the spectral data measured with all pixels first in red, green, blue and white. Measurements shall be made at the center of the panel.



(6) Definition of Optical Measurement Setup:

The LCD module should be stabilized at a given temperature for 20 minutes to avoid abrupt temperature change during measuring. In order to stabilize the luminance, the measurement should be executed after lighting backlight for 20 minutes.





5. TFT Electrical Characteristics

5.1 Absolute Maximum Rating (Ta=25 °C, VSS=0V)

Characteristics	Symbol	Min	Max	Unit
Digital Supply Voltage	VDD	-0.3	4.6	V
Digital Interface Supply Voltage	IOVCC	-0.3	4.6	
Operating Temperature	ТОР	-20	+70	°C
Storage Temperature	TST	-30	+80	°C

NOTE: If the absolute maximum rating of the above parameters is exceeded, even momentarily, the quality of the product may be degraded. Absolute maximum ratings specify the values which the product may be physically damaged if exceeded. Be sure to use the product within the range of the absolute maximum ratings.

5.2 DC Electrical Characteristics

Characteristics	Symbol	Min	Тур.	Max	Unit	Note
Digital Supply Voltage	VCI	2.5	3.3	4.2	V	
Digital Interface Supply Voltage	IOVCC	1.65	3.3	4.2	V	
Normal Mode Current	IDD		5		mA	
Level Input Voltage	VIH	0.7IOVCC		IOVCC	V	
Level input voltage	VIL	GND		0.3IOVCC	V	
Level Output Voltage	VOH	0.8IOVCC		IOVCC	V	
Level Sulput Voluge	VOL	GND		0.2IOVCC	V	



Item **Symbol** Min Max Unit Note Typ. 90 120 Forward Current IF mА --V Forward Voltage VF 3.2 ----384 Note 3 LCM Luminance LV 350 cd/m2 LED lifetime Hr 50000 hour Note1 ----& 2 80 % Note 3 Uniformity AVg ___ __

y b

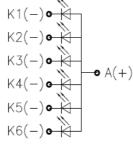
LED Backlight Characteristics

5.3

The back-light system is edge-lighting type with 6 white LEDs.

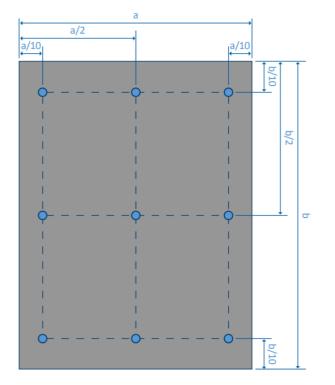
Note 1: LED lifetime (Hr) can be defined as the time in which it continues to operate under the condition: $Ta=25\pm3$ °C, typical IL value indicated in the above table until the brightness becomes less than 50%.

Note 2: The "LED lifetime" is defined as the module brightness decrease to 50% original brightness at Ta= 25° C and IL=120mA. The LED lifetime could be decreased if operating IL is larger than 120mA. The constant current driving method is suggested.



Backlight LED Circuit

Note 3: Luminance Uniformity of these 9 points is defined as below:



 $Luminance = (\underline{Total \ Luminance \ of \ 9 \ points})}{9}$

Uniformity =<u>minimum luminance in 9 points(1-9)</u> maximum luminance in 9 points(1-9)



6. AC Characteristic

6.1 Parallel RGB Interface Characteristics

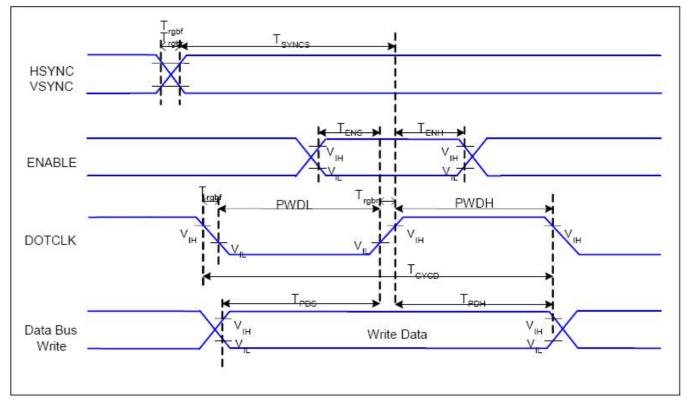


Figure 6.1: Parallel RGB Interface Timing Diagram

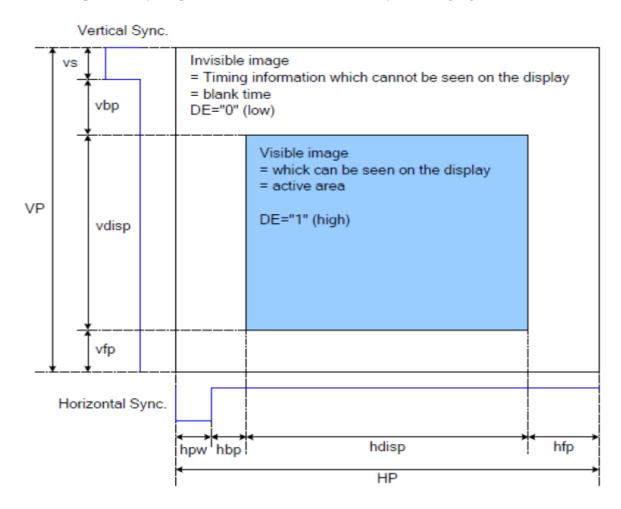
Signal	Symbol	Parameter	Min	Max	Unit	Description
HSYNC, VSYNC	T _{SYNCS}	VSYNC, HSYNC Setup Time	30	-	ns	
	T_{ENS}	Enable Setup Time	25	-	ns	
ENABLE	T_{ENH}	Enable Hold Time	25	-	ns	
	PWDH	DOTCLK High-level Pulse Width	60	-	ns	
	PWDL	DOTCLK Low-level Pulse Width	60	-	ns	
DOTCLK	T _{CYCD}	DOTCLK Cycle Time	120	-	ns	
	T_{RGHR}, T_{RGHF}	DOTCLK Rise/Fall Time	-	20	ns	
DB	$T_{\mathrm{DB}S}$	DB Data Setup Time	50	-	ns	
מט	$T_{\mathrm{DB}H}$	DB Data Hold Time	50	_	ns	

Table 6.1: Parallel RGB Interface Timing Characteristics



6.2 Timing Tables

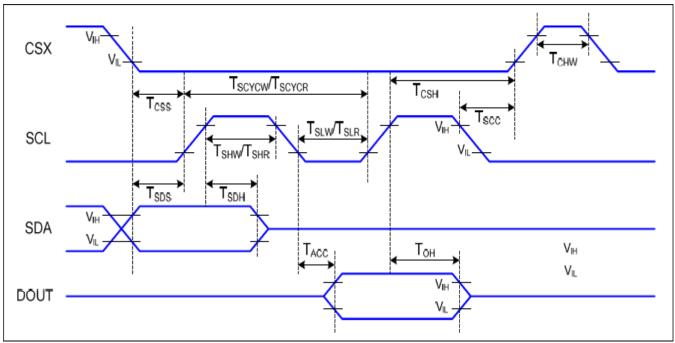
The display operation via the RGB interface is synchronized with the VSYNC, HSYNC and DOTCLK signals. The data can be written only within the specified area with low power consumption by using the window address function. The back porch and front porch are used to set the RGB interface timing signals.



Parameter	Symbol	Min	Тур	Max	Unit
DCLK cycle time	dclk	120	-		ns
Horizontal sync width	hpw	2	10	16	dclk
Horizontal back porch	hbp	2	20	24	dclk
Horizontal front porch	hfp	2	10	16	dclk
Vertical sync width	vs	1	2	4	Line
Vertical back porch	vbp	1	2		Line
Vertical front porch	vfp	3	4		Line

Table 6.2: RGB Interface Timing Table





6.3 Display Serial Interface Characteristics (3-line SPI system)

1

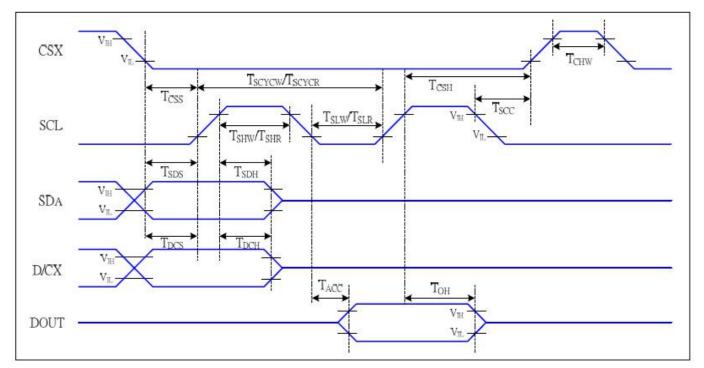
Figure 6.3: Serial Interface 3-SPI Timing Diagram

Signal	Symbol	Parameter	Min	Max	Unit	Description
	T _{CSS}	Chip select setup time (write)	15		ns	
	T _{CSH}	Chip select hold time (write)	15		ns	
CSX	T _{CSS}	Chip select setup time (read)	60		ns	
	T _{SCC}	Chip select hold time (read)	65		ns	
	T _{CHW}	Chip select "H" pulse width	40		ns	
	T _{SCYCW}	Serial clock cycle (write)	66		ns	
	T _{SHW}	SCL "H" pulse width (write)	15		ns	
SCL	T _{SLW}	SCL "L" width (write)	15		ns	
SCL	T _{SCYCR}	Serial clock cycle (read)	150		ns	
	T _{SHR}	SCL "H" pulse width (read)	60		ns	
	T _{SLR}	SCL "L" pulse width (read)	60		ns	
	T _{SDS}	Data setup time	30			
SDA (DIN)	T _{SDH}	Data hold time	30		ns	
	T _{ACC}	Access time	10	50		For max
SDA (DOUT)	T _{OH}	Output disable time	15	50	ns	CL=30pF For min CL=8pF

 Table 6.3: 3-line Serial Interface Timing Characteristics

Note: The rising time and falling time (Tr, Tf) of input signal are specified at 15 ns or less. Logic high and low levels are specified as 30% and 70% of VDDI for Input signals





6.4 Display Serial Interface Characteristics (4-line SPI serial)

Figure 6.4: Serial Interface 4-SPI Timing Diagram

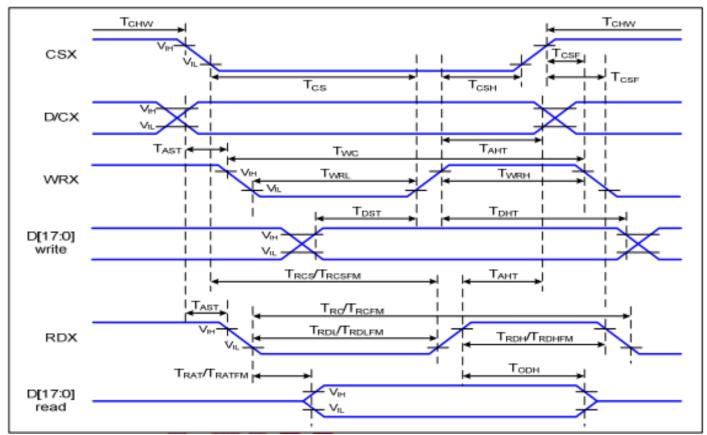
Signal	Symbol	Parameter N		Max	Unit	Description	
	T _{CSS}	Chip select setup time (write)	15		ns		
	T _{CSH}	Chip select hold time (write)	15		ns		
CSX	T _{CSS}	Chip select setup time (read)	60		ns		
	T _{SCC}	Chip select hold time (read)	65		ns		
	T _{CHW}	Chip select "H" pulse width	40		ns		
	T _{SCYCW}	Serial clock cycle (write)	66		ns		
	T _{SHW}	SCL "H" pulse width (write)	15		ns	write command &	
CCI	T _{SLW}	SCL "L" width (write)	15		ns	data ram	
SCL	T _{SCYCR}	Serial clock cycle (read)	150		ns		
Γ	T _{SHR}	SCL "H" pulse width (read)	60		ns	read command &	
	T _{SLR}	SCL "L" pulse width (read)	60		ns	data ram	
D/CX	T _{DCS}	D/CX setup time	10		ns		
D/CA	T _{DCH}	D/CX hold time	10		ns		
	T _{SDS}	Data setup time	10		ns		
SDA (DIN)	T _{SDH}	Data hold time	10		ns		
DOUT	T _{ACC}	Access time	10	50	ns	For max	
DOUT	T _{OH}	Output disable time	15	50	ns	CL=30pF For	
Table (5: A line Swind Laderbare Timing Changed midding min (

Table 6.5: 4-line Serial Interface Timing Characteristics

min CL=8pF

Note: The rising time and falling time (Tr, Tf) of input signal are specified at 15 ns or less. Logic high and low levels are specified as 30% and 70% of VDDI for Input signals.





6.5 8080 Series MCU Parallel Interface Characteristics: 18/16/9/8-bit Bus

Figure 6.5: Parallel Interface Timing Characteristics (8080-Series MCU Interface)

Signal	Symbol	Parameter	Min	Max	Unit	Description
D/CX	T _{AST}	Address setup time	0	-	ns	
	T _{AHT}	Address hold time (Write/Read)	10	-	ns	
CSX	T_{CHW}	Chip select "H" pulse width	0	-	ns	
	T _{CS}	Chip select setup time (Write)	15	-	ns	
	T _{RCS}	Chip select setup time (Read ID)	45	-	ns	
	T _{RCSFM}	Chip select setup time (Read FM)	355	-	ns	
	T _{CSF}	Chip select wait time (Write/Read)	10	-	ns	
	T _{CSH}	Chip select hold time	10	-	ns	
WRX	T _{WC}	Write cycle	66	-	ns	
	T _{WRH}	Control pulse "H" duration	15	-	ns	
	T _{WRL}	Control pulse "L" duration	15		ns	
RDX (ID)	T _{RC}	Read cycle (ID)	160	-	ns	
	T _{RDH}	Control pulse "H" duration (ID)	90	-	ns	
	T _{RDL}	Control pulse "L" duration	45	-	ns	
RDX (FM)	T _{RCFM}	Read cycle (FM)	450	-	ns	
	T _{RDHFM}	Control pulse "H" duration (FM)	90	-	ns	
	T _{RDLFM}	Control pulse "L" duration (FM)	355	-	ns	
D[17:0]	T _{DST}	Write data setup time	10	-	ns	
D[15:0],	T _{DHT}	Write data hold time	10	-	ns	For max CL=30pF
D[8:0],	T _{RAT}	Read access time (ID)	-	40	ns]
D[7:0]	T _{RATFM}	Read access time (FM)	-	340	ns	For min CL=8pF
	T _{ROD}	Output disable time	20	80	ns	

Table 6.5: 8080 Series MCU Parallel Timing Characteristics



6.3 Reset Timing

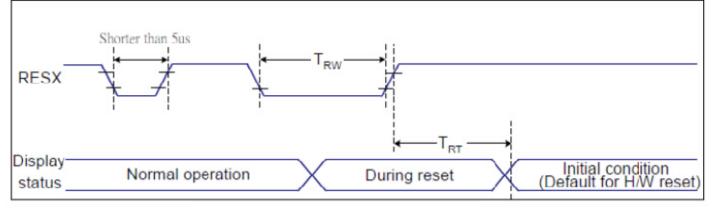


Figure 6.6: Reset Timing Diagram

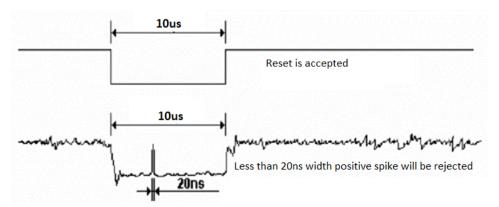
Related Pins	Symbol	Parameter	Min	Max	Unit
RESX	TRW	Reset pulse duration	10	-	us
	TRT	Reset cancel	-	5 (Note 1,5)	ms
				120 (Note 1, 6, 7)	ms

Notes:

- 1. The reset cancel includes also required time for loading ID bytes, VCOM setting and other settings from NVM (or similar device) to registers. This loading is done every time when there is HW reset cancel time (tRT) within 5ms after a rising edge of RESX.
- 2. Spike due to an electrostatic discharge on RESX line does not because irregular system reset according to the table below:

RESX Pulse	Action	
Shorter than 5us	Reset Rejected	
Longer than 9us	Reset	
Between 5us and 9 us	Reset starts	

- 3. During the resetting period, the display will be blanked (the display is entering blanking sequence, which maximum time is 120ms, when reset starts in Sleep Out mode. The display remains the blank state in Sleep in mode) and then return to Default condition for Hardware Reset.
- 4. Spike Rejection also applies during a valid reset pulse as shown below:



- 5. When Reset applied during Sleep In Mode.
- 6. When Reset applied during Sleep Out Mode.
- 7. It is necessary to wait 5ms after releasing RESX before sending commands. Also Sleep Out command cannot be sent for 120ms.



7. Cautions and Handling Precautions

7.1 Handling and Operating the Module

- 1. When the module is assembled, it should be attached to the system firmly. Do not warp or twist the module during assembly work.
- 2. Protect the module from physical shock or any force. In addition to damage, this may cause improper operation or damage to the module and back-light unit.
- 3. Note that polarizer is very fragile and could be easily damaged. Do not press or scratch the surface.
- 4. Do not allow drops of water or chemicals to remain on the display surface. If you have the droplets for a long time, staining and discoloration may occur.
- 5. If the surface of the polarizer is dirty, clean it using some absorbent cotton or soft cloth.
- 6. The desirable cleaners are water, IPA (Isopropyl Alcohol) or Hexane. Do not use ketene type materials (ex. Acetone), Ethyl alcohol, Toluene, Ethyl acid or Methyl chloride. It might permanent damage to the polarizer due to chemical reaction.
- 7. If the liquid crystal material leaks from the panel, it should be kept away from the eyes or mouth. In case of contact with hands, legs, or clothes, it must be washed away thoroughly with soap.
- 8. Protect the module from static; it may cause damage to the CMOS ICs.
- 9. Use fingerstalls with soft gloves in order to keep display clean during the incoming inspection and assembly process.
- 10. Do not disassemble the module.
- 11. Protection film for polarizer on the module shall be slowly peeled off just before use so that the electrostatic charge can be minimized.
- 12. Pins of I/F connector shall not be touched directly with bare hands.
- 13. Do not connect, disconnect the module in the "Power ON" condition.
- 14. Power supply should always be turned on/off by the item Power On Sequence & Power Off Sequence.

7.2 Storage and Transportation

- 1. Do not leave the panel in high temperature, and high humidity for a long time. It is highly recommended to store the module with temperature from 0 to 35 °C and relative humidity of less than 70%
- 2. Do not store the TFT-LCD module in direct sunlight.
- 3. The module shall be stored in a dark place. When storing the modules for a long time, be sure to adopt effective measures for protecting the modules from strong ultraviolet radiation, sunlight, or fluorescent light.
- 4. It is recommended that the modules should be stored under a condition where no condensation is allowed. Formation of dewdrops may cause an abnormal operation or a failure of the module. In particular, the greatest possible care should be taken to prevent any module from being operated where condensation has occurred inside.
- 5. This panel has its circuitry FPC on the bottom side and should be handled carefully in order not to be stressed.